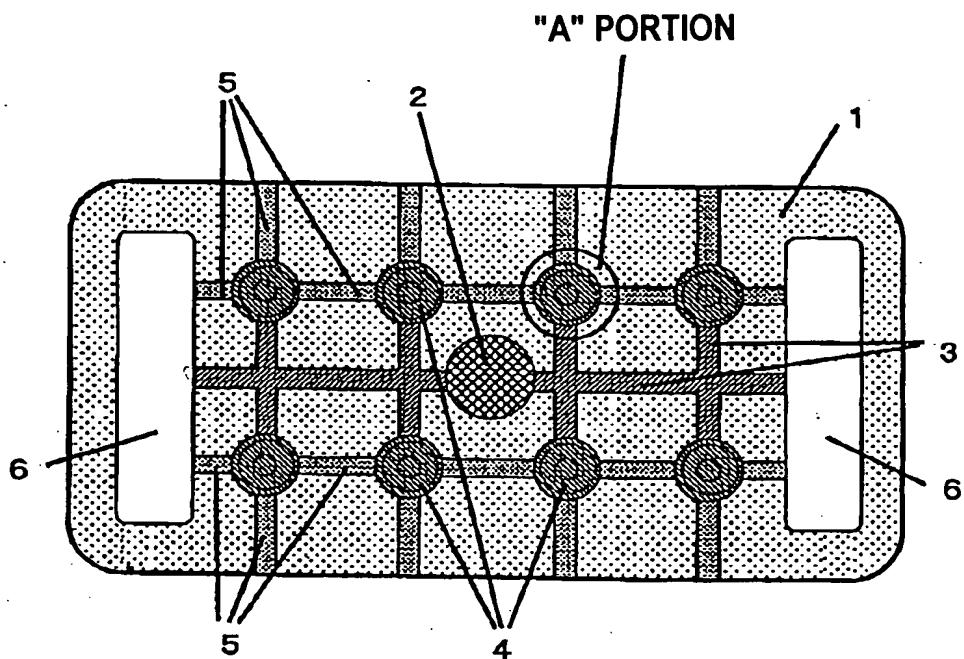


Inventor(s) : KURODA, Hirofumi
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Filing Date : Concurrent Herewith
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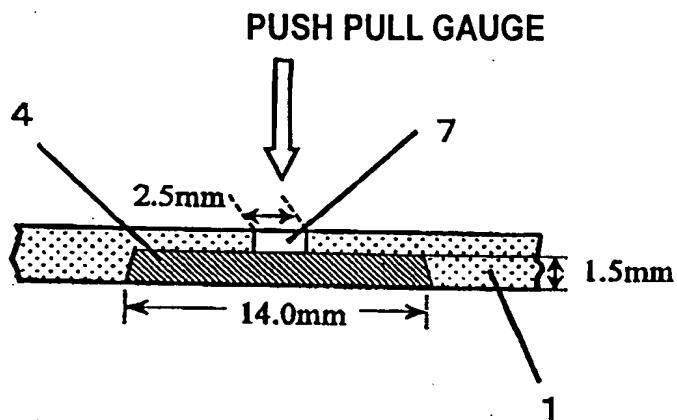
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Fig.1



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Fig.2



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Fig.3

